

(1.27 mm) .050"

LPAF SERIES

HIGH-SPEED LOW PROFILE OPEN-PIN-FIELD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?LPAF

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Current Rating:

2.2 A per pin

(6 adjacent pins powered)

Working Voltage:

250 VAC

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

Mates with:

LPAM

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



HIGH-SPEED CHANNEL PERFORMANCE

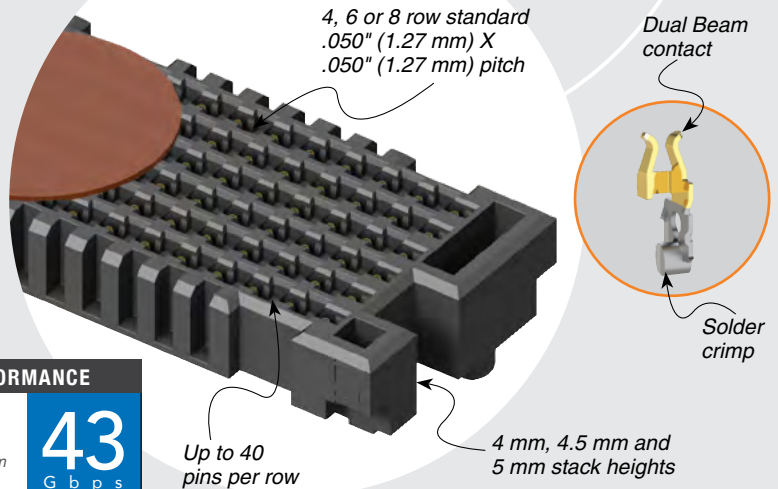
LPAM/LPAF @ 5 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

43
Gbps

Up to 40 pins per row

4 mm, 4.5 mm and 5 mm stack heights



4, 6 or 8 row standard
.050" (1.27 mm) X
.050" (1.27 mm) pitch

Dual Beam contact

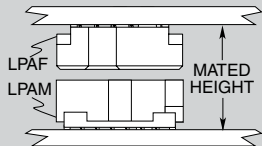
Solder crimp

ALSO AVAILABLE (MOQ Required)

- Tin-Lead Solder Charge
 - Other pins/row and row counts
 - Other Gold plating options
- Contact Samtec.

LPAF	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	K	TR
	-10, -20, -30, -40 (Per Row)	-03.0 = (3.0 mm) .118" -03.5 = (3.5 mm) .138"	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows -06 = Six Rows -08 = Eight Rows	-2 = Lead-Free Solder Crimp	-K = Polyimide film Pick & Place Pad	-TR = Tape & Reel

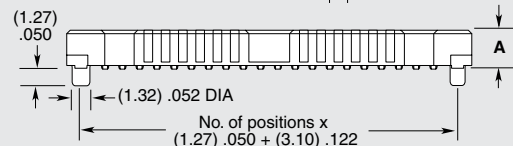
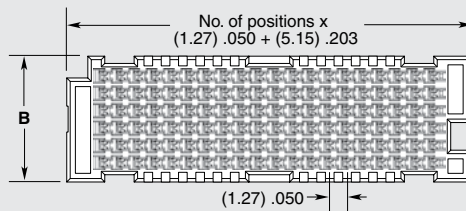
MATED HEIGHT



MATED HEIGHT*		
LPAF LEAD STYLE	LPAM LEAD STYLE	
	-01.0	-01.5
-03.0	(4.00) .157	(4.50) .177
-03.5	(4.50) .177	(5.00) .197

*Processing conditions will affect mated height.

NO. OF ROWS	B
-04	(6.71) .264
-06	(9.25) .364
-08	(11.79) .464



LEAD STYLE	A
-03.0	(2.79) .110
-03.5	(3.30) .130

Note: Patent Pending

Note: Some sizes, styles and options are non-standard, non-returnable.